

Vol. 03

The International Association of Electrical,
Electronic and Energy Engineering

NEWS LETTER

ICHVR 2024

2024 2nd International
Conference on Haptics
and Virtual Reality

ISEEIE 2024

2024 4th International
Symposium on Electrical,
Electronics and Information
Engineering

IAEEEE

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The International Association of
Electrical, Electronic and Energy
Engineering

ICHVR 2024

2024 2nd International Conference
on Haptics and Virtual Reality

Barcelona, Spain

September 20-22, 2024

www.ichvr.org

inquiry@ichvr.org



ISEEIE 2024

2024 4th International Symposium
on Electrical, Electronics and
Information Engineering

Leicester, UK

September 26-28, 2024

www.iseeie.org

info@iseeie.org



2024 2nd International Conference on Haptics and Virtual Reality



Conference Introduction

The 2024 2nd International Conference on Haptics and Virtual Reality (ICHVR 2024) will be held during Barcelona, Spain on September 20-22, 2024.

ICHVR 2024 is to bring together innovative academics and experts in the field of Haptics, Virtual Reality, Human-Computer Interaction, Computer Vision, Computer Arts, Mobile Intelligent Device and Artificial Intelligent Algorithm to a vibrant and vital forum. Leading researchers, students and engineers from around the world will exchange the latest advances through papers and oral presentations.

The conference welcomes the submission of papers in the nature of original research and technical reviews from but not limited to the above areas.

We cordially invite you to participate and contribute to ICHVR 2024.

CFP TOPICS

Authors are invited to submit full papers describing original research work in areas including, but not limited to:

- 3D Display, Tracking and Sensing
- 3D Interaction
- Active Touch Sensing and Behavior
- Augmented and Mixed Reality
- ChatGPT-based Applications
- Computer Vision
- Disturbance Rejection Haptics
- Embedded Haptics
- Haptic Interface Design and Control
- Haptic Sensors and Actuators
- Human-Computer Interaction
- Human-Robot Haptic Interaction
- Modeling, Simulation and Animation
- Multi-modal Systems
- Navigation
- Neural Control
- Neuroscience of Touch
- Optical Engineering
- Pattern Recognition
- Physical Human-robot Interaction
- Robotic Manipulation
- Tactile Displays
- Tracking and Sensing
- Virtual Reality

Submission

1. Manuscripts submitted to the conference should be written in English only.
2. Manuscripts submitted to the conference should follow the template provided: Full Paper Template, Abstract Template
3. Manuscripts can be submitted in Doc, Docx and PDF format.
4. Oral or Poster presentations should be nominated while submitting an abstract.
5. The ordinary length is suggested no less than 5 pages, including all figures, tables, references, and appendices. If the paper exceeds 5 pages, the additional pages will be charged at the time of registration.

Online Submission System

<https://cmt3.research.microsoft.com/User/Login?ReturnUrl=%2FICHVR2024>

Contact

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ISEEIE 2024

www.iseeie.org

2024 4th International Symposium on Electrical, Electronics and Information Engineering

2024 4th International Symposium on Electrical, Electronics and Information Engineering (ISEEIE 2024) will be held in University of Leicester, Leicester, UK on September 26-28, 2024.

This symposium serves as a paramount platform to foster collaboration and ignite innovation among Electrical, Electronics, and Information Engineers, as well as artificial intelligence and data scientists. With a vision to bring together experts and enthusiasts from diverse backgrounds, this symposium aims to transcend disciplinary boundaries and pave the way for ground-breaking advancements in the interconnected fields of electrical engineering, electronics, and information technology.

This symposium is to facilitate an exchange of ideas, research findings, and technological advancements that transcend traditional silos. We strive to create an environment that encourages interdisciplinary collaboration, bringing together professionals and researchers from various domains, including but not limited to electrical and electronics engineering, information technology, artificial intelligence, aerospace, transportation and energy. By integrating these domains seamlessly, we envision unlocking new horizons for efficiency, scalability, capability, safety, and accessibility in autonomous and intelligent systems. This integration serves as a catalyst for innovation, not only through theoretical advancements but also by extending to practical applications in engineered substrates.



ISEEIE 2024

www.iseeie.org/commit.html

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Zhiwei Gao
Northumbria University
UK
IEEE Fellow

Honorary Chair



Jonathon A Chambers
University of Leicester
UK
IEEE Fellow, FREng

Conference Chair



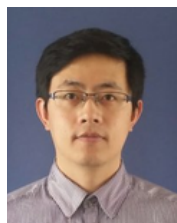
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Science
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Conference Co-Chair



Yihua Hu
King's Collidge London
UK
IET Fellow



CFP Topics

Electrical and Electronics Engineering

- Automation and Control Engineering
- Circuits and Systems
- Computer network and Security
- Computer-aided Design and Manufacturing
- Electrotechnologies
- Electrical Machines and Drive Systems
- High-Performance Motor System
- High Voltage and Insulation Technologies
- Power Systems Communication
- Remote Sensing, Radar and Sensing

Information Engineering

- Artificial Intelligence
- Bioinformatic
- Computational Optics
- Computer and Information Science
- Computer Graphics and Image Processing
- Computer Science and Engineering
- Computer Simulation and Modeling
- Grid Computing
- Image Processing and Acquisition
- Information Management
- Transmission of Numerical Images

Online Submission

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